353094-1 ✓ ACTIVE

AMPMODU

TE Internal #: 353094-1

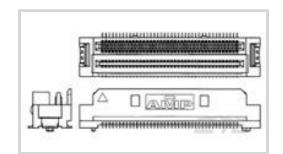
PCB Mount Hermaphroditic Connector, Vertical, Board-to-Board, 80 Position, .6 mm [.024 in] Centerline, Gold, Surface Mount, Signal,

Black

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Hermaphroditic Connector

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 80

Centerline (Pitch): .6 mm [.024 in]

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Hermaphroditic Connector
Connector System	Board-to-Board
Connector System	
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	80
Board-to-Board Configuration	Parallel

Body Features

Primary Product Color	Black	

Contact Features

Contact Mating Area Length	4.4 mm[.173 in]
PCB Contact Termination Area Plating Material Thickness	2 μm[78.74 μin]
Mating Tab Width	1.1 mm[.043 in]
Mating Tab Thickness	.2 mm[.008 in]
Contact Shape & Form	Square
PCB Contact Termination Area Plating Material	Tin



Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.5 μm[19.7 μin]
Contact Type	Hermaphroditic
Contact Current Rating (Max)	.5 A
Termination Features	
Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Rectangular Termination Post & Tail Width	.8 mm[.031 in]
Termination Method to Printed Circuit Board	Surface Mount
Mechanical Attachment	
PCB Mount Alignment Type	Positioning Bosses
PCB Mount Retention Type	Solder Peg
Mating Alignment	With
Mating Alignment Type	Polarized
PCB Mount Retention	With
PCB Mount Alignment	With
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	.6 mm[.024 in]
Housing Material	LCP (Liquid Crystal Polymer)
Dimensions	
Connector Height	4.2 mm[.17 in]
Stack Height	4 mm[.157 in]
PCB Thickness (Recommended)	1.6 mm[.62 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0

Packaging Features



Packaging Quantity	30
Packaging Type	Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 245°C

Product Compliance Disclaimer

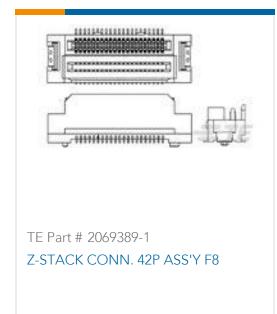
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

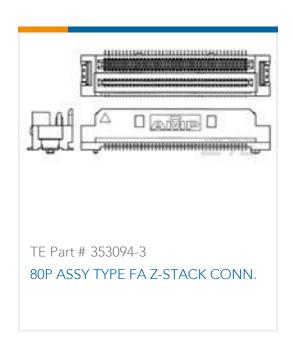










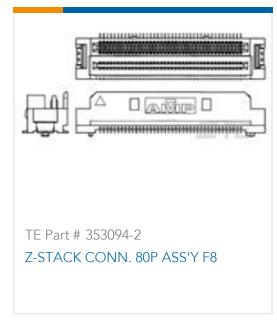


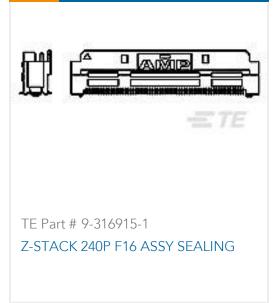
















Documents

Product Drawings

Z-STACK CONN. 80P ASS'Y F8

Japanese

CAD Files

3D PDF

English

Customer View Model

ENG_CVM_353094-1_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_353094-1_A.3d_igs.zip

English

Customer View Model

ENG_CVM_353094-1_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

PCB Mount Hermaphroditic Connector, Vertical, Board-to-Board, 80 Position, .6 mm [. 024 in] Centerline, Gold, Surface Mount, Signal, Black



Product Specification

English